

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Texas Instruments, et al.

Docket No: TI-26239.1

Serial No: 10/612,129

Examiner: Cao, Phat X.

Filed: 7/2/2003

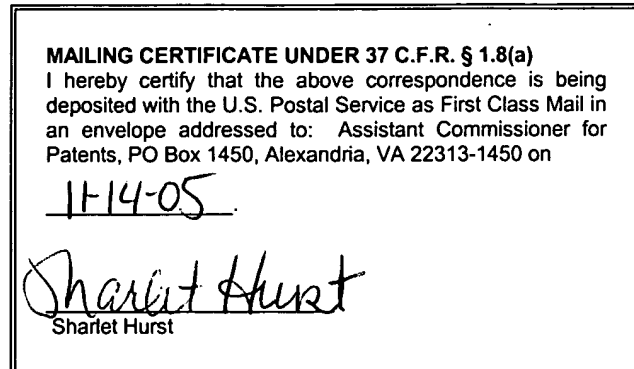
Art Unit: 2814

For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE

**INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97 & 1.98**

Assistant Commissioner for Patents  
Washington, DC 20231

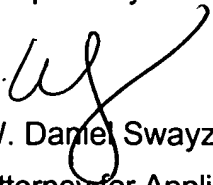
Dear Sir:



Applicants wish to bring to the attention of the Patent and Trademark Office the information noted on the enclosed PTO-1449. A copy of the noted references is enclosed herewith.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668, and please credit any excess fees to such Deposit Account. Any further necessary extension of time is hereby requested.

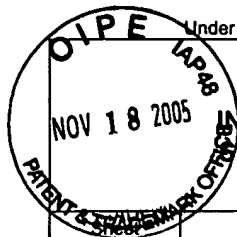
Respectfully submitted,

  
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### Complete If Known

|                      |              |
|----------------------|--------------|
| Application Number   | 10/612,129   |
| Filing Date          | 7/2/2003     |
| First Named Inventor | Yew          |
| Group Art Unit       | 2814         |
| Examiner Name        | Cao, Phat X. |
| Attorney Docket No.  | TI-26239.1   |

### U.S. PATENT DOCUMENTS

| Exam. Initials* | Cite No. <sup>1</sup> | U.S. Patent Document |                                   | Name of Patentee or Applicant of Cited Doc. | Date of Pub. of Cited Doc. (mm-dd-yyyy) | Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear |
|-----------------|-----------------------|----------------------|-----------------------------------|---|---|---|
|                 |                       | Number               | Kind Code <sup>2</sup> (if known) |   |   |   |
|                 | AA                    | 5,739,585            |                                   | Akram, et al.                               | 04-14-1998                              |   |
|                 | AB                    | 5,753,974            |                                   | Masukawa                                    | 05-19-1998                              |   |
|                 | AC                    |                      |                                   |   |   |   |
|                 | AD                    |                      |                                   |   |   |   |
|                 | AE                    |                      |                                   |   |   |   |
|                 | AF                    |                      |                                   |   |   |   |
|                 | AG                    |                      |                                   |   |   |   |
|                 | AH                    |                      |                                   |   |   |   |
|                 | AI                    |                      |                                   |   |   |   |
|                 | AJ                    |                      |                                   |   |   |   |

### FOREIGN PATENT DOCUMENTS

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|-----------------|-----------------------|-------------------------|---------------------|-----------------------------------|---|---|---|----------------|
|                 |                       | Office <sup>3</sup>     | Number <sup>4</sup> | Kind Code <sup>2</sup> (if known) |   |   |   |                |
|                 | BA                    | EP                      | 0 810 655 A2        |                                   | Goh   | 12-03-1997                              |   |                |
|                 | BB                    | DE                      | 19712551A1          |                                   | Kim   | 11-20-1997                              |   |                |
|                 | BC                    |                         |                     |                                   |   |   |   |                |
|                 | BD                    |                         |                     |                                   |   |   |   |                |
|                 | BE                    |                         |                     |                                   |   |   |   |                |
|                 | BF                    |                         |                     |                                   |   |   |   |                |
|                 | BG                    |                         |                     |                                   |   |   |   |                |
|                 | BH                    |                         |                     |                                   |   |   |   |                |
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<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

<sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

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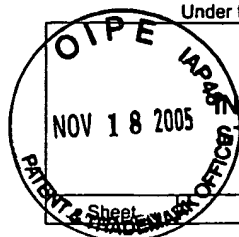


PTO/SB/08A (08-00)

Approved for use through 10/31/2002. OMB 0651-

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## Complete If Known

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| Group Art Unit       | 2814         |
| Examiner Name        | Cao, Phat X. |
| Attorney Docket No.  | TI-26239.1   |

## OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

| Exam. Initials* | Cite No. <sup>1</sup> | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.  | T <sup>2</sup> |
|-----------------|-----------------------|--|----------------|
|                 | CA                    | MATIENZO L J, et al. "Adhesion Issues in Electronic Packaging". Solid State Technology, Cowan Publ. Corp. Port Washington, NY US vol. 38, no. 7 July 1, 1995 pages 99-100, 102. XP000523397 ISSN: 0038-111X  |                |
|                 | CB                    | AMAGAI M, et al. "The Effect of Polyimide Surface Morphology and Chemistry on Package Cracking Induced by Interfacial Delamination". Reliability Physics Symposium, 1994, New York, NY USA, IEEE, April 11, 1994, pages 101-107. XP010117230 ISBN: 0-7803-1357-7 |                |
|                 | CC                    | IWABUCHI KAORU. "Semiconductor Device". Patent Abstracts of Japan. Vol. 1997, no. 06, June 30, 1997 & JP 09 036167 A (SONY CORP), February 7, 1997   |                |
|                 | CD                    | KIN ZAISHUN. "Semiconductor Package of Chip Scale and its Manufacture". Patent Abstracts of Japan. Vol. 1998, no. 09, July 31, 1998 & JP 10 098130 A, (SAMSUNG ELECTRON CO LTD), April 14, 1998.   |                |
|                 | CE                    |  |                |
|                 | CF                    |  |                |
|                 | CG                    |  |                |
|                 | CH                    |  |                |
|                 | CI                    |  |                |
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|--------------------|--|-----------------|--|
| Examiner Signature |  | Date Considered |  |
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